

# PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT																
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT																
<b>CONVEYING PARTY DATA</b>																	
<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 70%;">Name</th> <th style="width: 30%;">Execution Date</th> </tr> </thead> <tbody> <tr><td>Jen-Chi Chang</td><td>10/27/2011</td></tr> <tr><td>Chun-Li Lin</td><td>10/27/2011</td></tr> <tr><td>Kai-Shiung Hsu</td><td>10/27/2011</td></tr> <tr><td>Ming-Shiou Kuo</td><td>10/27/2011</td></tr> <tr><td>Wen-Long Lee</td><td>10/27/2011</td></tr> <tr><td>Po-Hsiung Leu</td><td>10/27/2011</td></tr> <tr><td>Ding-I Liu</td><td>10/27/2011</td></tr> </tbody> </table>		Name	Execution Date	Jen-Chi Chang	10/27/2011	Chun-Li Lin	10/27/2011	Kai-Shiung Hsu	10/27/2011	Ming-Shiou Kuo	10/27/2011	Wen-Long Lee	10/27/2011	Po-Hsiung Leu	10/27/2011	Ding-I Liu	10/27/2011
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<table border="1" style="width: 100%; border-collapse: collapse;"> <tr><td><b>Name:</b></td><td>Taiwan Semiconductor Manufacturing Company, Ltd.</td></tr> <tr><td><b>Street Address:</b></td><td>No. 8, Li-Hsin Rd. 6</td></tr> <tr><td><b>Internal Address:</b></td><td>Science-Based Industrial Park</td></tr> <tr><td><b>City:</b></td><td>Hsin-Chu</td></tr> <tr><td><b>State/Country:</b></td><td>TAIWAN</td></tr> <tr><td><b>Postal Code:</b></td><td>300-77</td></tr> </table>		<b>Name:</b>	Taiwan Semiconductor Manufacturing Company, Ltd.	<b>Street Address:</b>	No. 8, Li-Hsin Rd. 6	<b>Internal Address:</b>	Science-Based Industrial Park	<b>City:</b>	Hsin-Chu	<b>State/Country:</b>	TAIWAN	<b>Postal Code:</b>	300-77				
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<b>CORRESPONDENCE DATA</b>																	
<p>Fax Number: (214)200-0853</p> <p>Phone: 214-651-5000</p> <p>Email: ipdocketing@haynesboone.com</p> <p><i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i></p> <p>Correspondent Name: Haynes and Boone LLP</p> <p>Address Line 1: 2323 Victory Avenue</p> <p>Address Line 2: Suite 700</p> <p>Address Line 4: Dallas, TEXAS 75219</p>																	

OP \$40.00 13212904

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**PATENT**  
 REEL: 027199 FRAME: 0633

ATTORNEY DOCKET NUMBER:	2011-0090/24061.1804
NAME OF SUBMITTER:	David M. O'Dell
<p>Total Attachments: 8</p> <p>source=1804Assignment#page1.tif</p> <p>source=1804Assignment#page2.tif</p> <p>source=1804Assignment#page3.tif</p> <p>source=1804Assignment#page4.tif</p> <p>source=1804Assignment#page5.tif</p> <p>source=1804Assignment#page6.tif</p> <p>source=1804Assignment#page7.tif</p> <p>source=1804Assignment#page8.tif</p>	

Docket No.: 2011-0090 / 24061.1804

Customer No.: 42717

**ASSIGNMENT**

WHEREAS, we,

- |     |                |    |  |
|-----|----------------|----|--|
| (1) | Jen-Chi Chang  | of | 9F, No. 595-9, Sec. 2, Jingguo Road, North District<br>Hsinchu City 300, Taiwan, R.O.C.            |
| (2) | Chun-Li Lin    | of | 10F, No. 52, Shijie Street, East District<br>Hsinchu City 300, Taiwan, R.O.C.                      |
| (3) | Kai-Shiung Hsu | of | #3, Lane 277, Jing-Guo 3rd Road, San-Min Area<br>Kaohsiung, Taiwan, R.O.C.                         |
| (4) | Ming-Shiou Kuo | of | No. 117-7, Cingcyuan Road, Shalu District<br>Taichung City 433, Taiwan, R.O.C.                     |
| (5) | Wen-Long Lee   | of | 11F-2, No. 52, Lushui Road, East District<br>Hsinchu City 300, Taiwan, R.O.C.                      |
| (6) | Po-Hsiung Leu  | of | No. 49-5, Neighborhood 3, Chang-Sing Village<br>Lujhu Township, Taoyuan County 338, Taiwan, R.O.C. |
| (7) | Ding-I Liu     | of | 4F-2, No. 28, Tiyu Street, East District<br>Hsinchu City 300, Taiwan, R.O.C.                       |

have invented certain improvements in

**INTERLAYER DIELECTRIC STRUCTURE AND METHOD MAKING THE SAME**

for which we have executed an application for Letters Patent of the United States of America on  
August 18, 2011, as U.S. Serial No. 13/212,904; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office  
 information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6,  
 Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining  
 the entire right, title, and interest in, to and under the said invention and the said application in the  
 United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is  
 hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred  
 and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC,  
 its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the  
 said invention, and the said application, and all divisional, renewal, substitutional, and continuing  
 applications thereof, and all Letters Patent of the United States of America which may be granted  
 thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be  
 filed for said invention in any country or countries foreign to the United States of America, and all  
 extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a  
 filing priority of the above-described patent application may be obtained, including the right to collect

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past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

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Inventor Name: Jen-Chi Chang

Residence Address: 9F, No. 595-9, Sec. 2, Jingguo Road, North District  
Hsinchu City 300, Taiwan, R.O.C.

Dated: 2011.10.27

Jen-chi chang  
Inventor Signature

---

Inventor Name: Chun-Li Lin

Residence Address: 10F, No. 52, Shijie Street, East District  
Hsinchu City 300, Taiwan, R.O.C.

Dated: 2011.10.27

Chun-Li Lin  
Inventor Signature

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Inventor Name: Kai-Shiung Hsu

Residence Address: #3, Lane 277, Jing-Guo 3rd Road, San-Min Area  
Kaohsiung, Taiwan, R.O.C.

Dated: 2011. 10. 27

Kai-Shiung Hsu  
Inventor Signature

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Inventor Name: Ming-Shiou Kuo

Residence Address: No. 117-7, Cingeyuan Road, Shalu District  
Taichung City 433, Taiwan, R.O.C.

Dated: \_\_\_\_\_

\_\_\_\_\_  
Inventor Signature

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Inventor Name: Wen-Long Lee

Residence Address: 11F-2, No. 52, Lushui Road, East District  
Hsinchu City 300, Taiwan, R.O.C.

Dated: 2011. 10. 27

Wen-Long Lee  
Inventor Signature

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Inventor Name: Po-Hsiung Leu

Residence Address: No. 49-5, Neighborhood 3, Chang-Sing Village  
Lujhu Township, Taoyuan County 338, Taiwan, R.O.C.

Dated: 2011. 10. 27

Po-Hsiung Leu  
Inventor Signature

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APPENDIX


Docket No.: 2011-0090 / 24061.1804  
Customer No.: 42717

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Inventor Name: Ding-I Liu

Residence Address: 4F-2, No. 28, Tiyu Street, East District  
Hsinchu City 300, Taiwan, R.O.C.

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Inventor Name: Jen-Chi Chang

Residence Address: 9F, No. 595-9, Sec. 2, Jingguo Road, North District  
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Inventor Name: Chun-Li Lin

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Inventor Name: Po-Hsiung Leu

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Dated: \_\_\_\_\_

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Inventor Signature